



## Final Product Change Notification

201907020F01

**Issue Date:** 16-Aug-2019

**Effective Date:** 13-Nov-2019

Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#)

**This notice is NXP Company Proprietary.**



### Change Category

- |  |   |  |   |   |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process             | <input type="checkbox"/> Assembly Process   | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials           | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input checked="" type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location  | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware                      | <input type="checkbox"/> Other              |  |   |   |

i.MX6ULL Fab Site  
Transfer from SMIC8  
to SMICB2

### Description of Change

NXP Semiconductors announces the Wafer Fabrication site transfer for i.MX6ULL associated with this notification from the current SMIC8, Shanghai, China Wafer Fabrication site to the SMICB2, Beijing, China Wafer Fabrication site.

Wafer Fabrication site transfer was successfully qualified adhering to NXP specifications.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-PW-13

### Reason for Change

SMIC8 wafer Fabrication site will cease production for 40nm technology production line and need transfer the products to internal SMICB2 Wafer Fabrication site.

Qualification of SMICB2 Wafer Fabrication site is required for customer supply assurance.

### Identification of Affected Products

Product identification does not change

There is no change to orderable part number. The tracecode marking on the device includes datecode.

NXP will have traceability by datecode.

## Product Availability

### Sample Information

Samples are available from 16-Sep-2019

Below are the sample part numbers that will be made available.

- PCIMX6Y2CVM08AB
- PCIMX6Y2DVM09AB

### Production

Planned first shipment 01-Jan-2020

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Equivalent wafer fabrication process currently used at SMIC8 wafer manufacturing facility will be implemented at SMICB2.

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Additional information

Affected products and sales history information: see attached file

Self qualification: [view online](#)

Additional documents: [view online](#)



## Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 15-Sep-2019.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** Fubin Yao  
**Position** Product Engineer  
**e-mail address** [fubin.yao@nxp.com](mailto:fubin.yao@nxp.com)

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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